

Title (en)

Process for making electrical-circuit boards.

Title (de)

Verfahren zur Herstellung von elektrischen Leiterplatten.

Title (fr)

Procédé de fabrication de plaques de circuit électrique.

Publication

EP 0324189 A2 19890719 (DE)

Application

EP 88121921 A 19881231

Priority

DE 3800682 A 19880113

Abstract (en)

Circuit boards with conductor tracks having good adhesion are obtained by chemically or mechanically removing the cladding from the substrate boards which are clad with copper foil on both sides, activating and, optionally, sensitising them, providing them with a 0.05-2.0 μm thick layer composed of nickel, cobalt, manganese, or a nickel/iron or nickel/cobalt mixture in an electroless metallisation bath, applying a 0.5-5.0 μm thick copper layer in a subsequent copper bath and building up the conductor pattern thereon by standard semi-additive methods.

Abstract (de)

Leiterplatten mit gut haftenden Leiterbahnen erhält man, wenn man die Basisplatten, die beidseitig mit Kupferfolien kaschiert sind, chemisch oder mechanisch von dieser Kaschierung befreit, aktiviert, gegebenenfalls sensibilisiert, in einem stromlosen Metallisierungsbath mit einer 0,05 -2,0 μm starken Schicht aus Nickel, Kobalt, Mangan, einem Nickel/Eisen-oder Nickel/ Kobalt-Gemisch versieht, in einem darauffolgenden Kupferbad eine 0,5-5,0 μm dicke Kupferschicht aufbringt und darauf nach üblichen Semiadditivmethoden das Leiterbild aufbaut.

IPC 1-7

H05K 3/18; H05K 3/38

IPC 8 full level

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CPC (source: EP US)

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Cited by

US5827604A; EP0598273A1; US6023842A; EP0624054A3; US5523174A

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